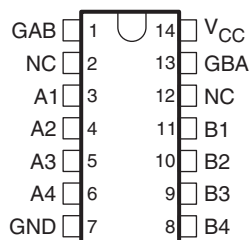


QUADRUPLE BUS TRANSCEIVERS

FEATURES

- Two-Way Asynchronous Communication Between Data Buses
- PNP Inputs Reduce D-C Loading
- Hysteresis (Typically 400 mV) at Inputs Improves Noise Margin

SN54LS243 . . . J OR W PACKAGE
SN74LS243 . . . D, N, OR NS PACKAGE
(TOP VIEW)



**FUNCTION TABLE
(EACH TRANSCEIVER)**

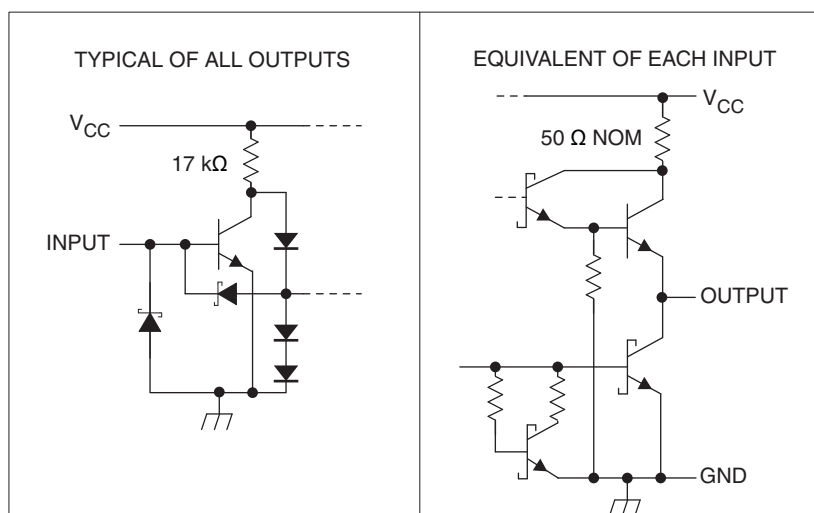
INPUTS		SNxxLS243
$\overline{\text{GAB}}$	GBA	
L	L	A to B
H	H	B to A
H	L	Isolation
L	H	Latch A and B (A = B)

DESCRIPTION

These four-data-line transceivers are designed for asynchronous two-way communications between data buses. SN74LS243 can be used to drive terminated lines down to 133 Ω .

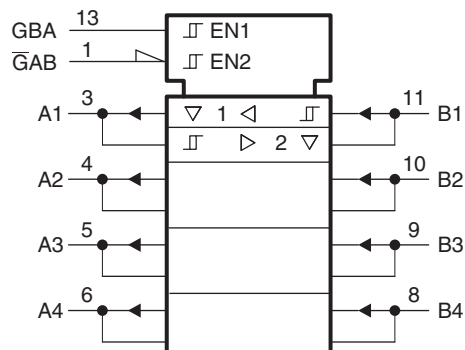
SN54LS243 is characterized for operation over the full military temperature range of -55°C to 125°C . SN74LS243 is characterized for operation from 0°C to 70°C .

SCHEMATICS OF INPUTS AND OUTPUTS



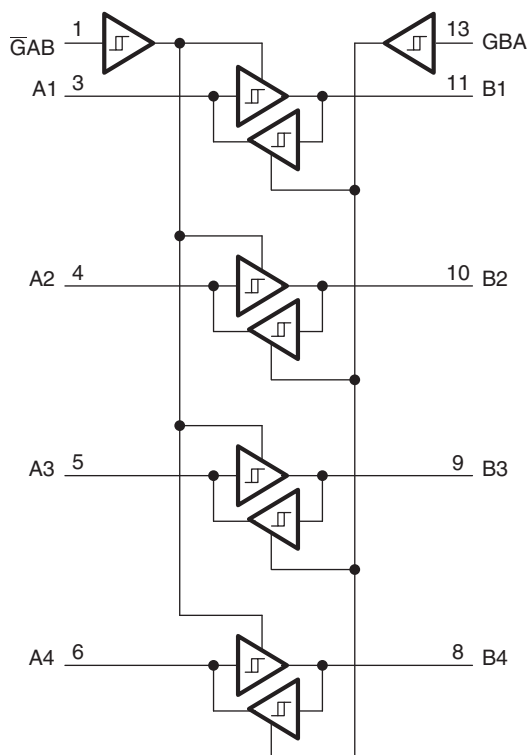
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LOGIC SYMBOL



A. These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾		7		V
V _{IN}	Input voltage		7		V
OFF-state output voltage			5.5		V
T _A	Operating free-air temperature range	SN54LS243	−55	125	°C
		SN74LS243	0	70	
T _{stg}	Storage temperature range		−65	150	°C

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Voltage values are with respect to network ground terminal.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		SN54LS243			SN74LS243			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage ⁽¹⁾	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
I _{OH}	High-level output voltage			–12			–15	mA
I _{OL}	Low-level output voltage			12			24	mA
T _A	Operating free-air temperature	–55		125	0		70	°C

- (1) Voltage values are with respect to network ground terminal.

ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS ⁽¹⁾		SN54LS243			SN74LS243			UNIT
				MIN	TYP ⁽²⁾	MAX	MIN	TYP ⁽²⁾	MAX	
V _{IK}	A or B	V _{CC} = MIN, I _I = −18 mA		−1.5			−1.5			V
Hysteresis (V _{T+} − V _{T−})		V _{CC} = MIN,		0.2	0.4		0.2	0.4		V
V _{OH}		V _{CC} = MIN, V _{IH} = 2 V,	V _{IL} = MAX, I _{OH} = −3 mA	2.4	3.1		2.4	3.1		V
			V _{IL} = 0.5 V, I _{OH} = MAX	2			2			
V _{OL}		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX	I _{OL} = 12 mA	0.25 0.4		0.25 0.4				V
			I _{OL} = 24 mA			0.35 0.5				
I _{OZH}		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX,	V _O = 2.7 V	40			40			μA
I _{OZL}		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX,	V _O = 0.4 V	−200			−200			μA
I _I	A or B	V _{CC} = MAX,	V _I = 5.5 V	0.1			0.1			mA
	$\overline{\text{GAB}}$ or GBA		V _I = 7 V	0.1			0.1			
I _{IH}		V _{CC} = MAX,		20			20			μA
I _{IL}	A inputs	V _{CC} = MAX, V _I = 0.4 V, GAB and GBA at 0 V		−0.2			−0.2			mA
	B inputs	V _{CC} = MAX, V _I = 0.4 V, GAB and GBA at 4.5 V		−0.2			−0.2			
	$\overline{\text{GAB}}$ or GBA	V _{CC} = MAX, V _I = 0.4 V,		−0.2			−0.2			
I _{OS}		V _{CC} = MAX		−40	−225		−40	−225		mA
I _{CC}	Outputs high	V _{CC} = MAX, (3)	Outputs open,	22	38		22	38		mA
	Outputs low			29	50		29	50		
	All outputs disabled			32	54		32	54		

(1) For conditions shown as MIN or MAX, use the appropriate value specified under "recommended operating conditions."

(2) All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.(3) I_{CC} is measured with transceivers enabled in one direction only, or with all transceivers disabled.**SWITCHING CHARACTERISTICS** $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	SN54LS243			SN74LS243			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	$R_L = 667 \Omega, C_L = 45 \text{ pF}$		9	14		12	18	ns
t_{PHL}			12	18		12	18	ns
t_{PZL}			20	30		20	30	ns
t_{PZH}			15	23		15	23	ns
t_{PLZ}	$R_L = 667 \Omega, C_L = 5 \text{ pF}$		10	20		10	20	ns
t_{PHZ}			15	25		15	25	ns

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
8002002CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J	Samples
8002002DA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002002DA SNJ54LS243W	Samples
SN54LS243J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS243J	Samples
SN74LS243D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS243	Samples
SN74LS243DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS243	Samples
SN74LS243N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS243N	Samples
SN74LS243NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS243N	Samples
SNJ54LS243J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002002CA SNJ54LS243J	Samples
SNJ54LS243W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8002002DA SNJ54LS243W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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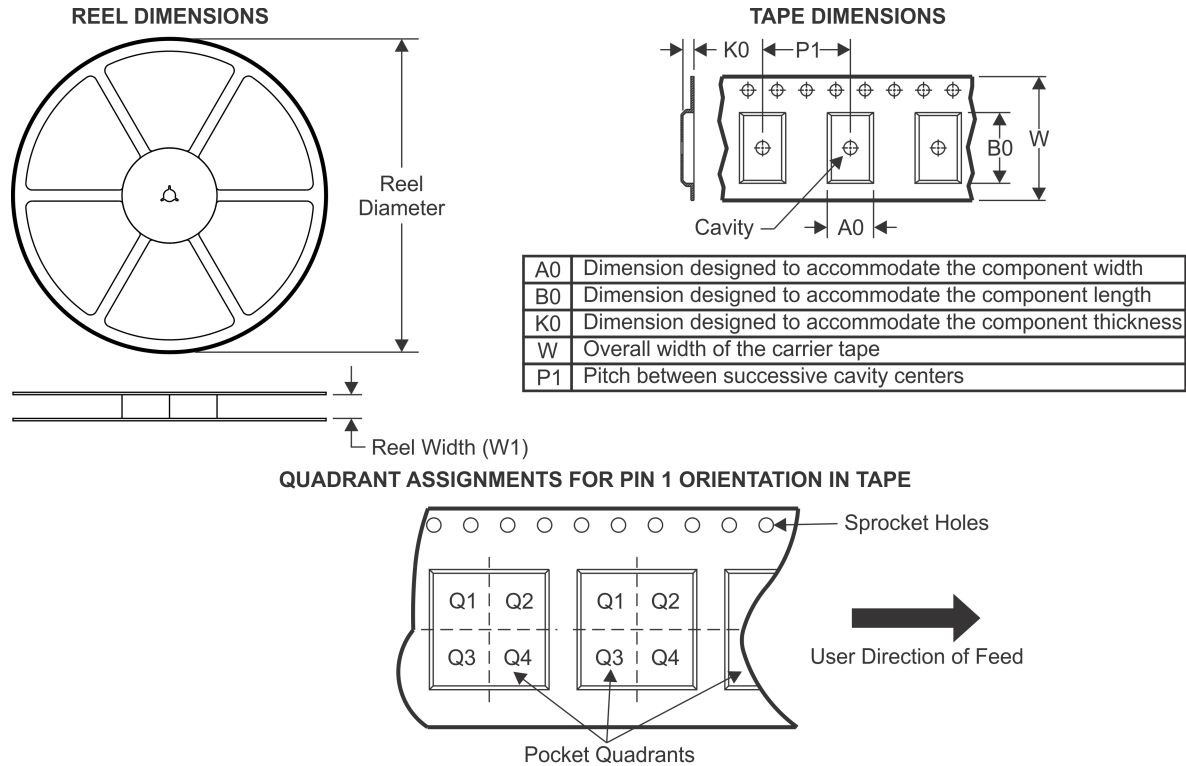
OTHER QUALIFIED VERSIONS OF SN54LS243, SN74LS243 :

- Catalog : [SN74LS243](#)
- Military : [SN54LS243](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

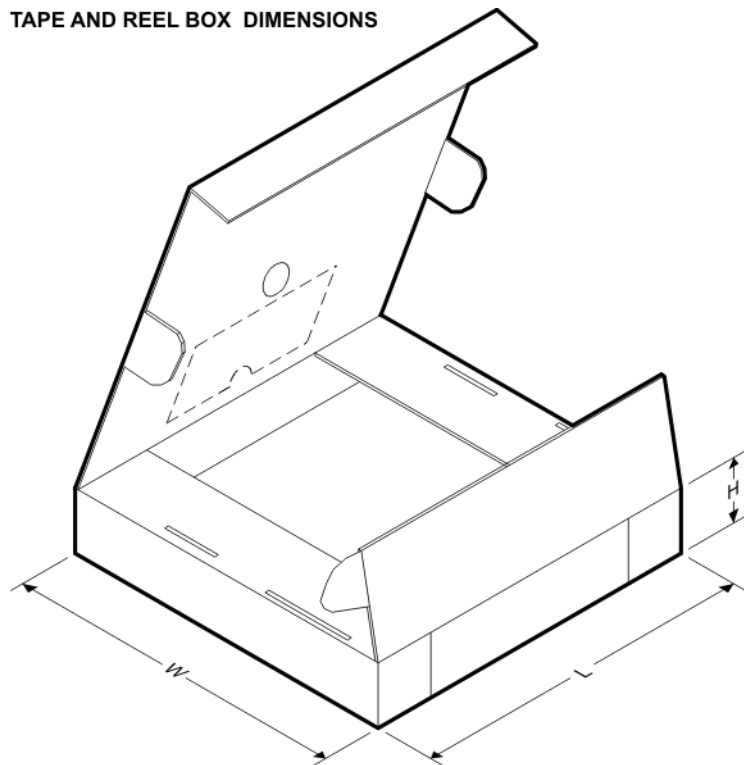
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS243DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

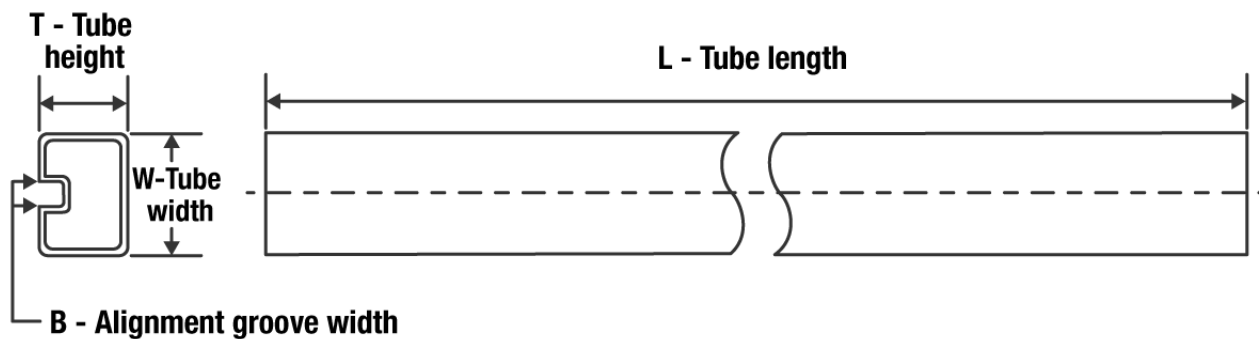
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS243DR	SOIC	D	14	2500	853.0	449.0	35.0

TUBE

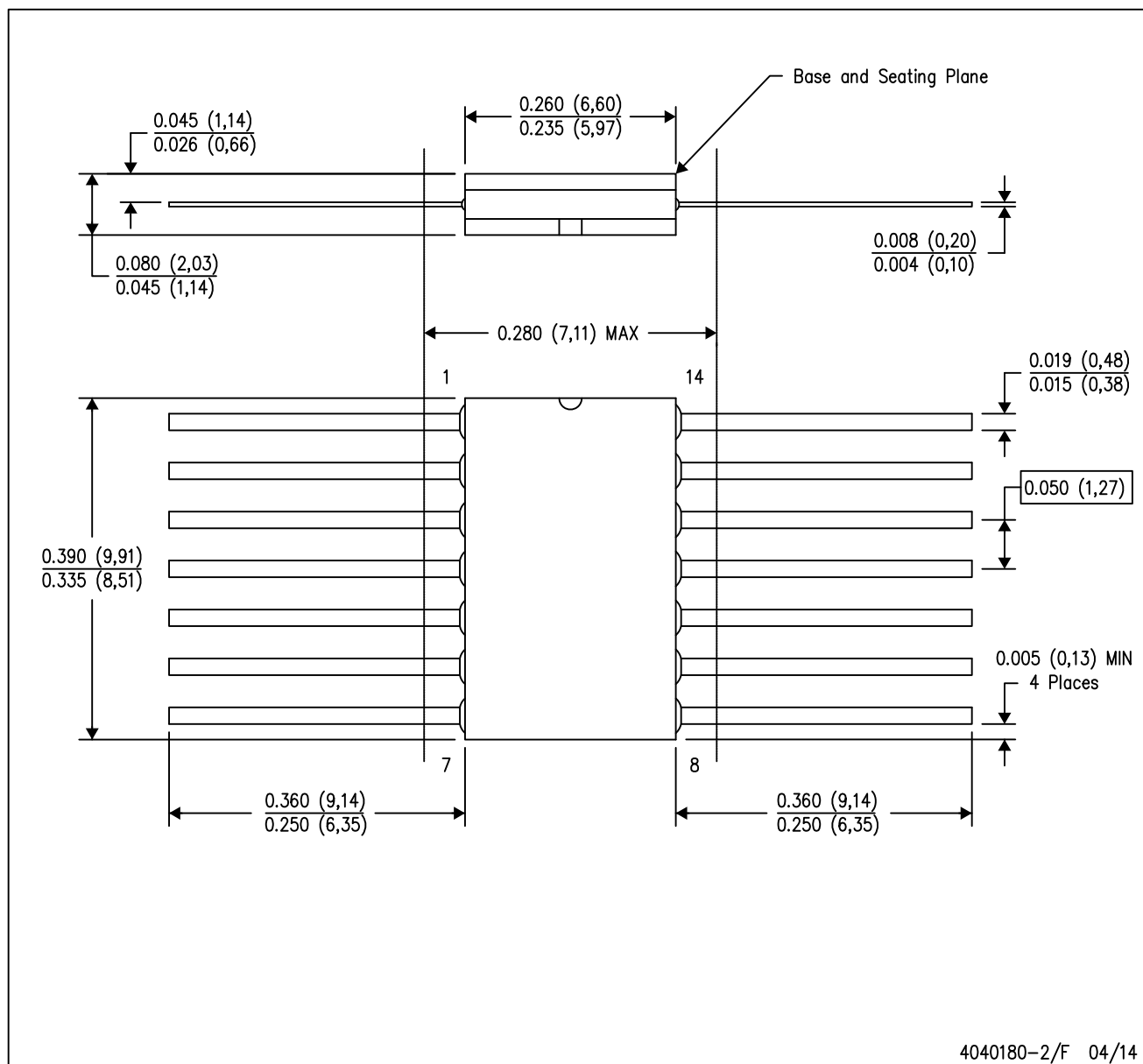


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LS243D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS243N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS243NE4	N	PDIP	14	25	506	13.97	11230	4.32

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



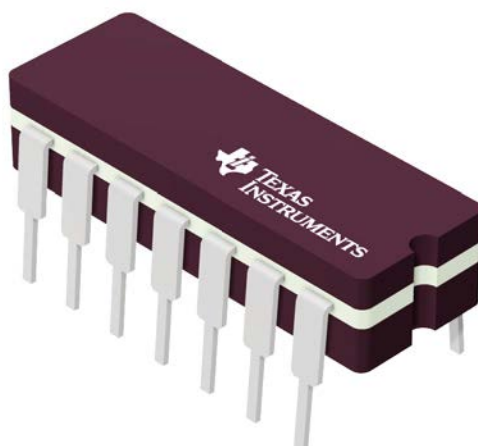
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14

J 14

GENERIC PACKAGE VIEW

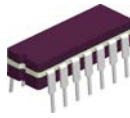
CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE

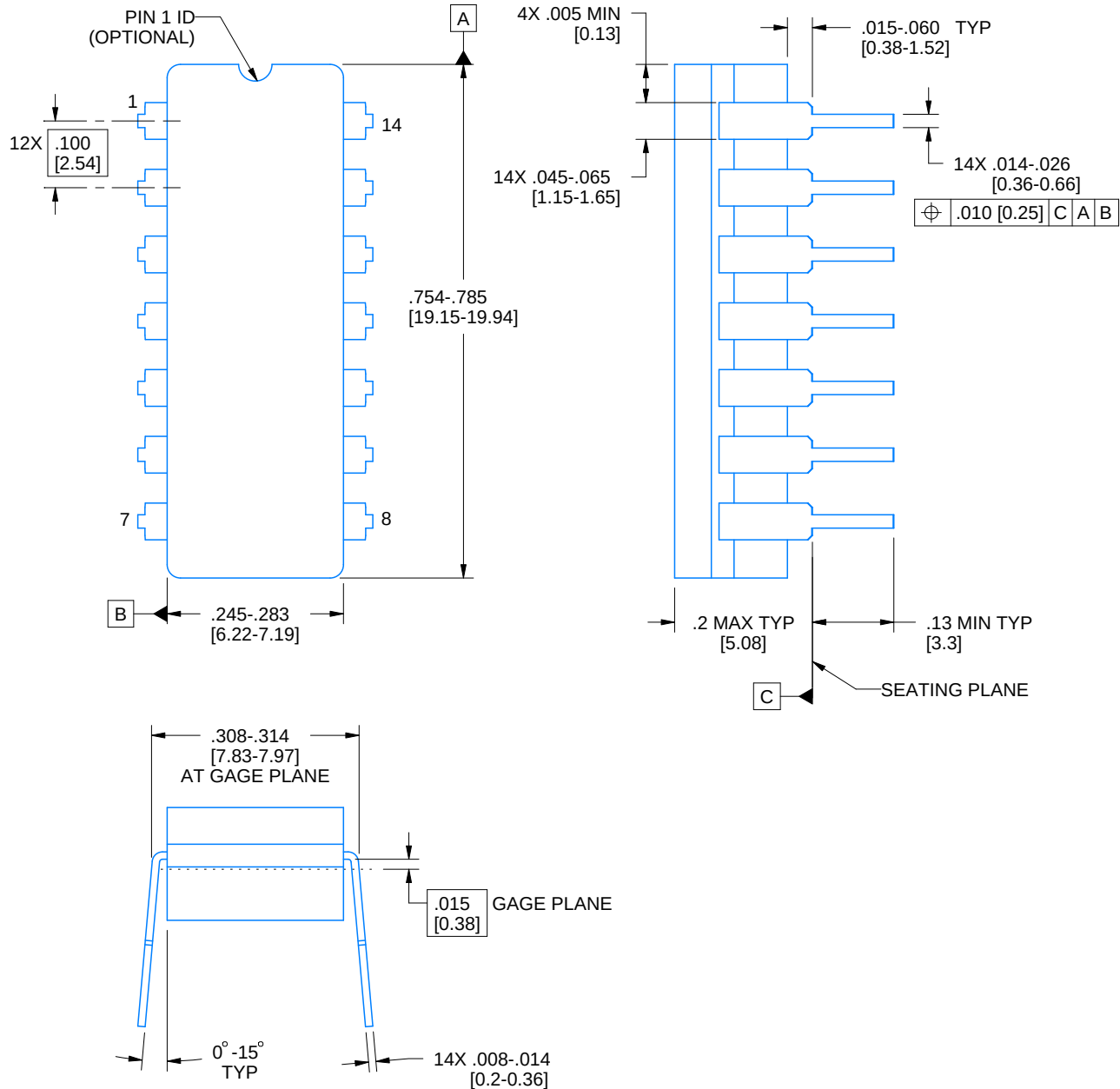


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A**PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



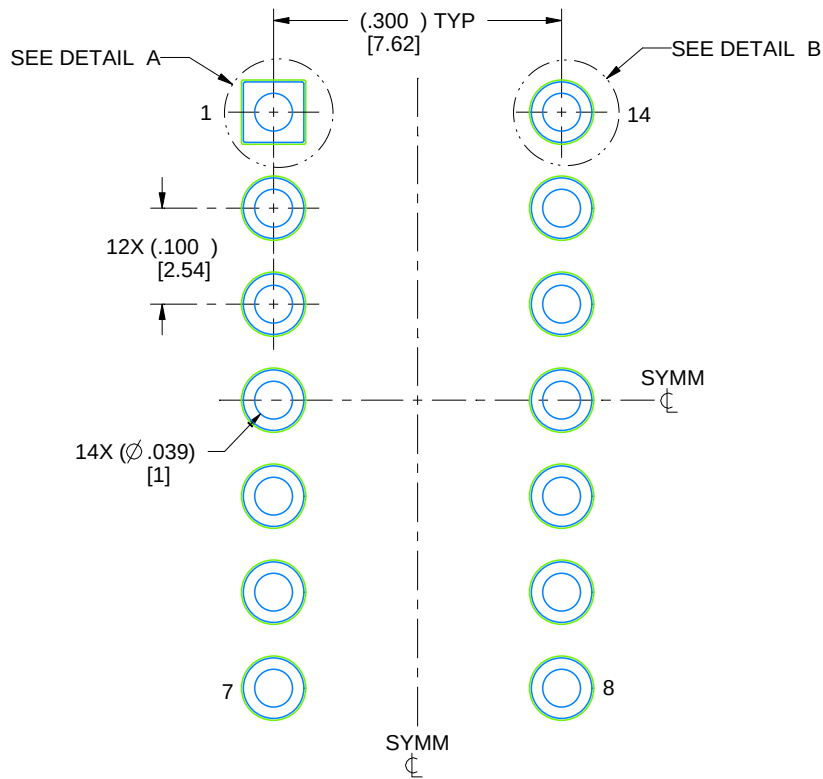
**TEXAS
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EXAMPLE BOARD LAYOUT

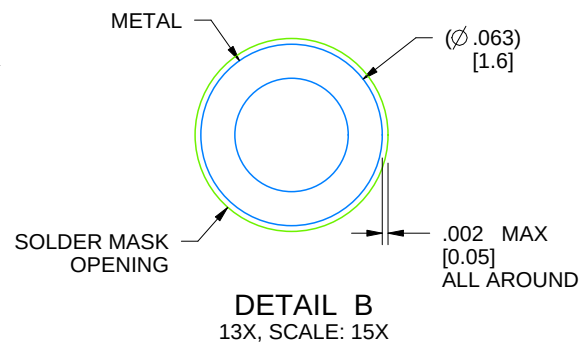
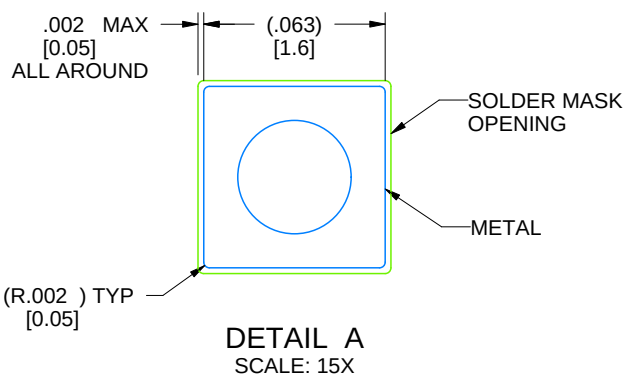
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



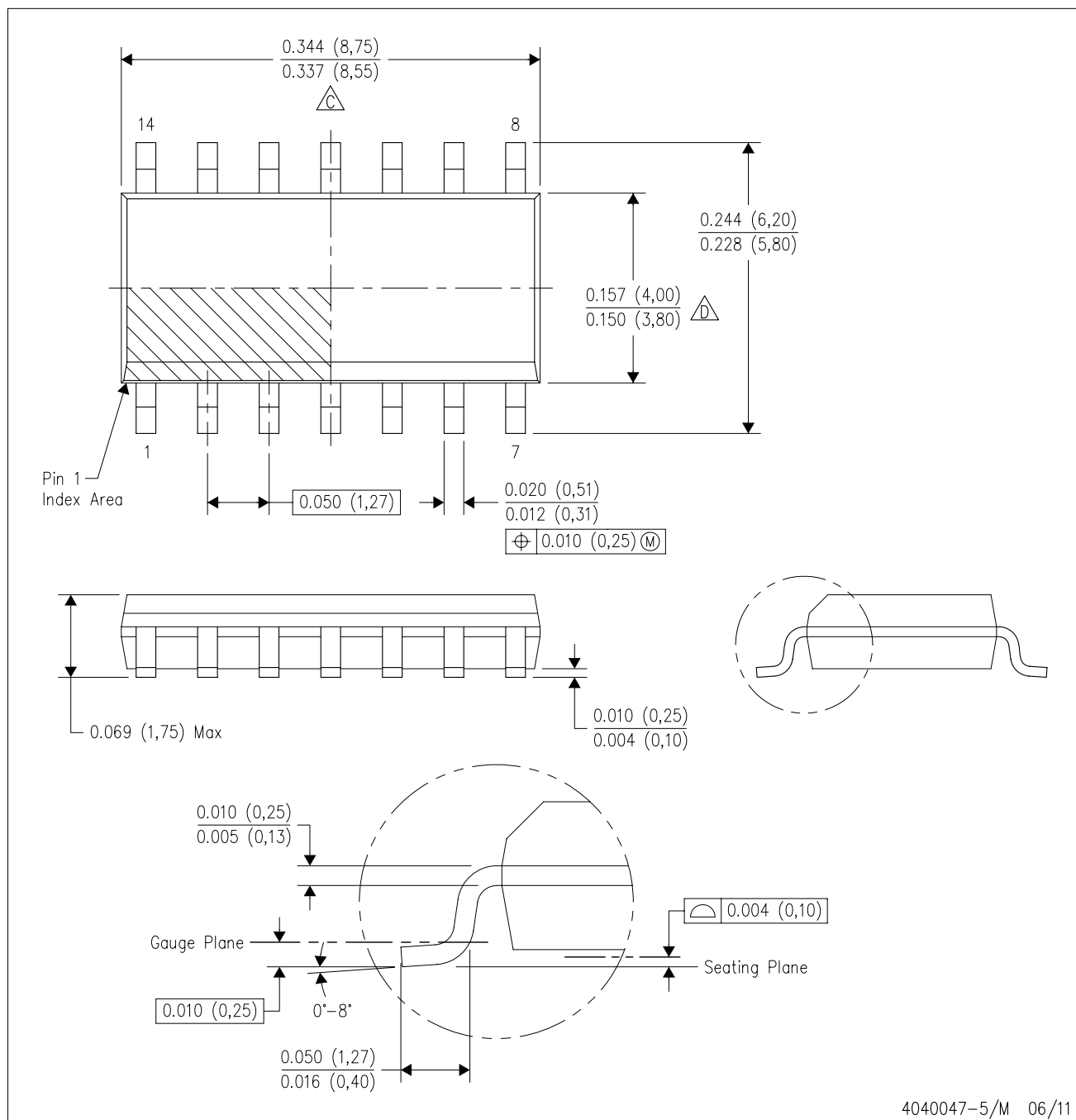
LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



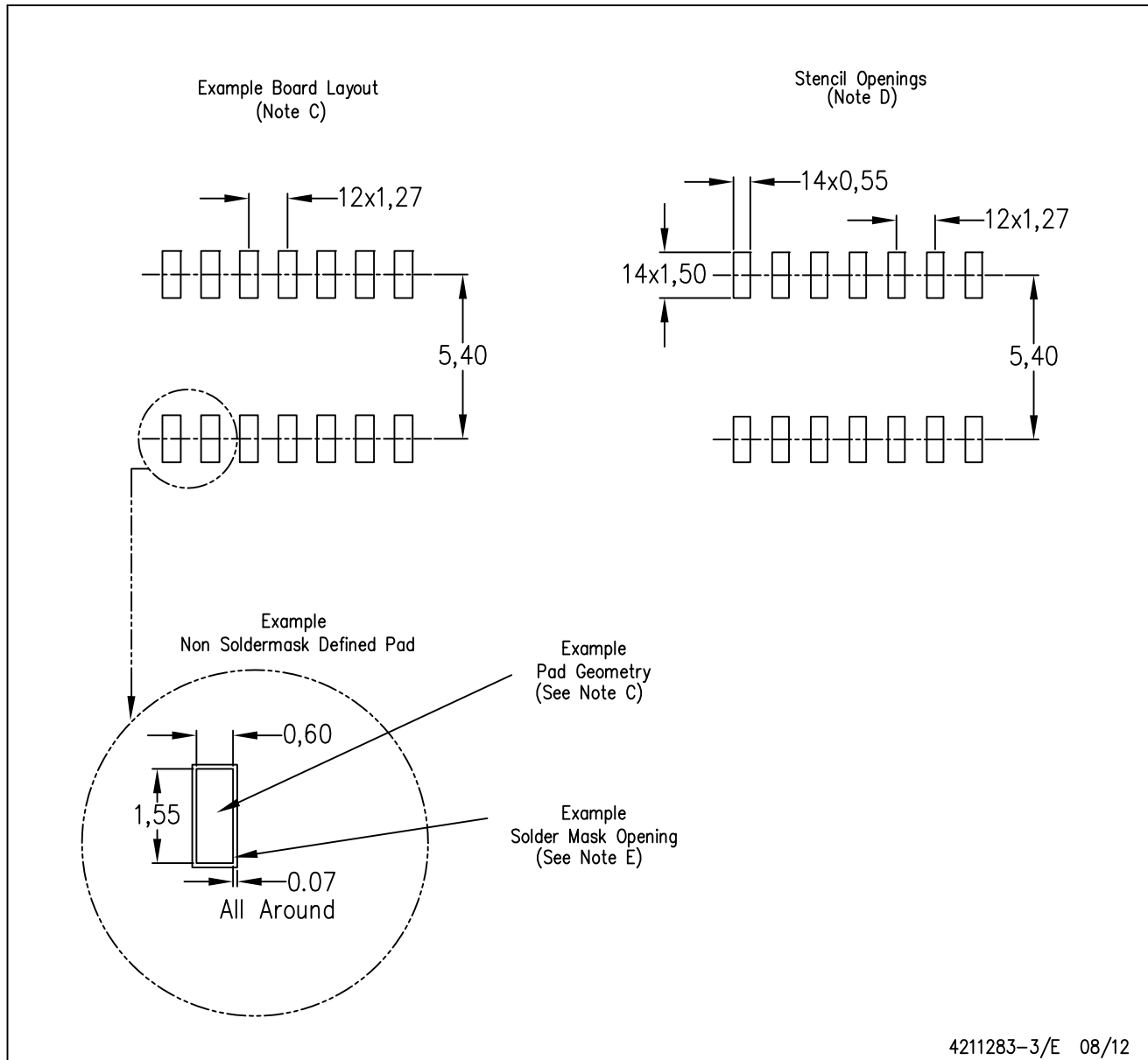
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

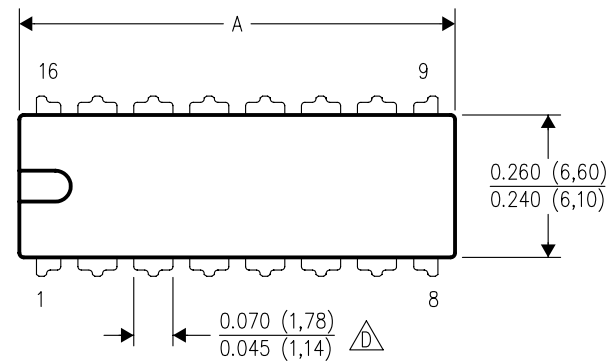


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

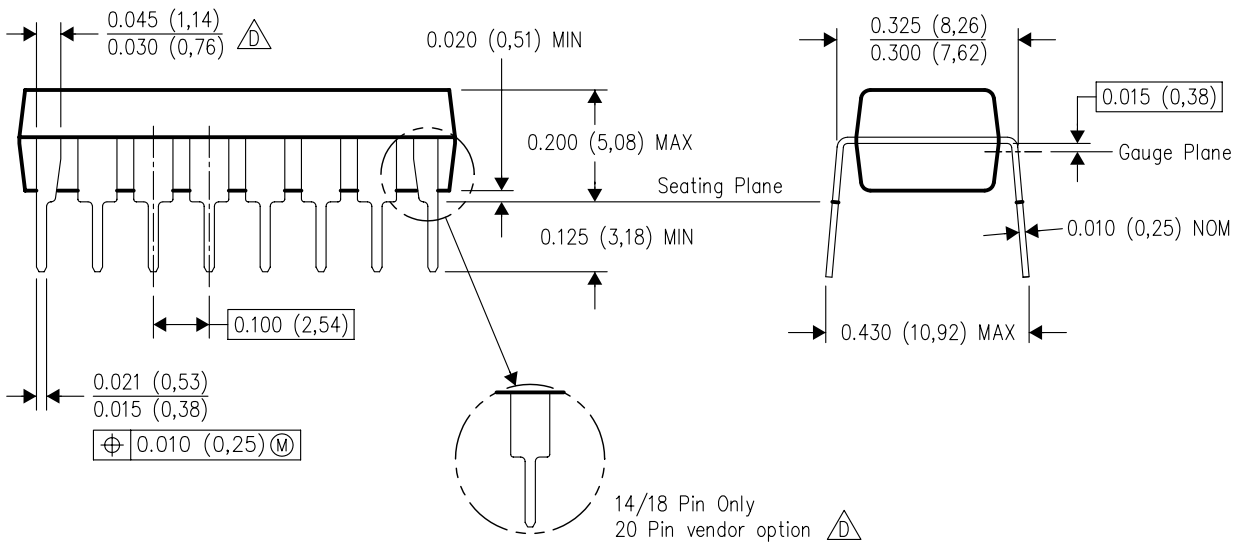
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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